

RACON 8, SMT, 2.5 N, 1 NO

LBL_NRFND



fields of application

- > Measurement-control-regulation
- > Mechanical and system engineering
- > Automotive
- > Electro-medical

special features

- > Gold contacts, reliable switching with low currents
- > Special tactile feedback
- > Different operating forces
- > Variable overall heights due to plunger
- > Terminal technology: SMT or THT
- > Traceability through product identification

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description

Our top-quality RACON 8 tactile switches – in dimensions 8.4 x 8.4 mm – feature an unmistakeable click, high switching reliability, and a sealed contact system. That has made RACON the standard in many industries. Whether for automotive applications, systems with keycaps, or membrane keyboards, RACON impresses in the THT or SMT versions – for your application too.

RACON 8 tactile switches can be arranged individually, in rows or as key blocks. When used beneath membrane overlays, the RACON key switches should be combined with plungers. Suitable for the most important soldering techniques.

- > Soldering bath for THT versions
- > Reflow soldering for SMT versions
- > Vapor phase soldering for SMT versions
- > Manual soldering
- > Processing of the SMT designs with SMT automatic assembly machines
- > IMDS entry

technical data

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Color blue
Operating temperature, min. -40 °C

Operating temperature, max. 90 °C
Storage temperature, min. -50 °C
Storage temperature, max. 85 °C
illuminated No
Soldering Reflow

Solder heat resistance according

to standard

Packaging

> R∆FLe

> RAFI eCatalog

direct links

The information in this data sheet only contains general descriptions and / or performance features, which may not apply precisely as described to the respective application, and which my change due to further product enhancements. The technical data, illustrations and other information about our products are the mere results of individual technical testing. These descriptions and other product features are only binding if they expressly agreed upon at the time of the conclusion of a binding contract. In all other cases, we reserve the right to make technical changes as well as changes of availability. Pictures and other graphic illustrations are approximations only. All product names may be trademarks or brand names of the RAFI Group or any other sub-supplier of RAFI. The use of such by any third parties for their own purposes may infringe the rights of the respective entity holding those rights.

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Blister

DIN EN 60068-2-58

RAFI GmbH & Co. KG



Packaging unit 1,000 pcs.

Operating life 1,000,000 cycles B10 1,300,000 cycles

MSL Moisture Sensitivity Level 1
Corrosive gas testing according to Yes

standard

MOQ order 1,000 pcs.

RoHS compliant Yes
REACH compliant Yes

Component material Elastomer

> mounting diameters

Outside dimension, length 8.4 mm
Outside dimension, width 8.4 mm

Installation height 5.1 ± 0.15 mm Grid, min. 8.9×12.7 mm

> mechanical data

Actuation function momentary contact function

Operating force, min. 2.5 N
Switching travel 0.6 mm
Contact function 1 NO

Contact system Snap-action contact

SPST - Single Pole Single Throw

Contact material Gold
Solderability Yes
Terminal on the rear SMT

> electrical data

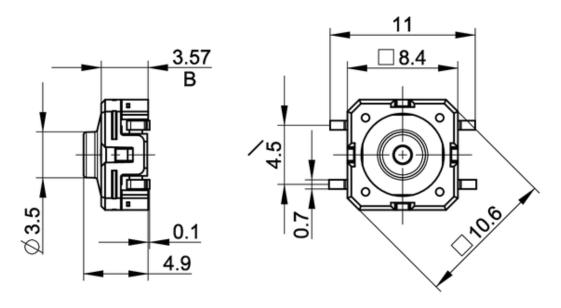
Rated voltage, min. 0.02 V Rated voltage, max. 35 V

Rated current, min. 0.00001 A
Rated current, max. 0.1 A
Rated power, max. 1 W

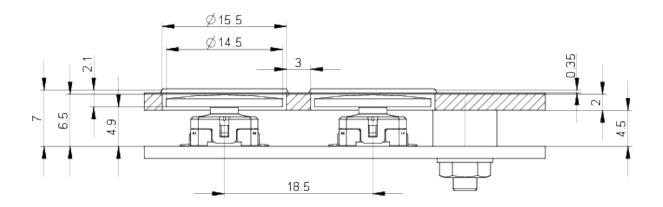


drawings

Dimensioned drawing

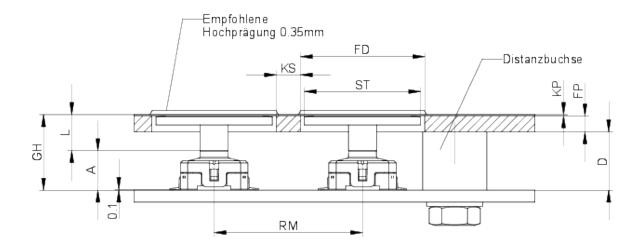


System drawing

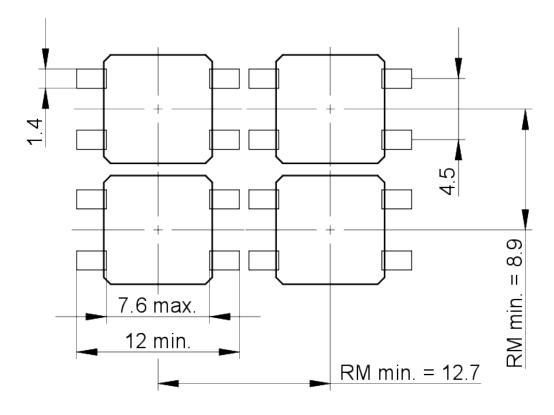




System drawing

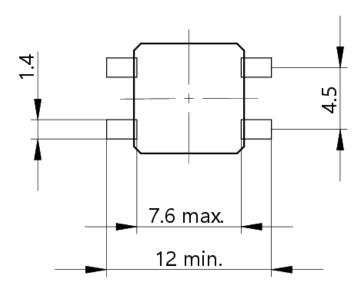


PCB drawing



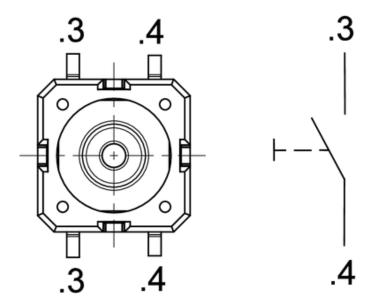


PCB drawing



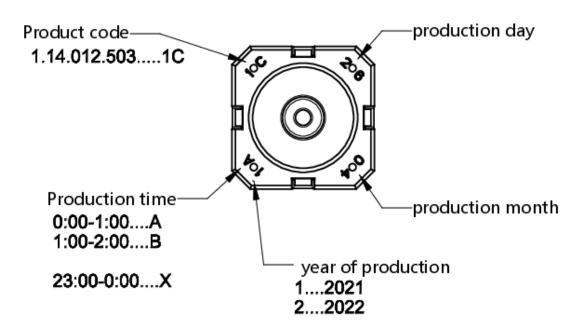
PCB-Pad component side

Schematic diagram

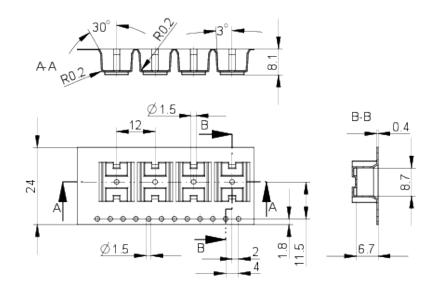




Product labeling drawing



Packaging drawing



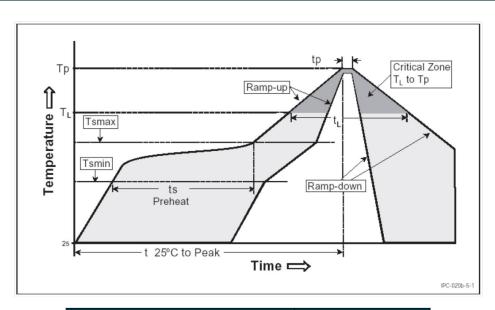


mounting

RAFI soldering profile for ROHS compliant reflow components



Publication date: October 7, 2021



Parameter	RAFI values		
Gradient (T _L to T _P)	max. 3°C / s		
Preheating zone Minimum temperature (T _{smin}) Maximum temperature (T _{smax}) Time (from min. to max.) (ts)	150°C 200°C 60 - 120 s		
Gradient (T _{smax} to T _L)	max. 3°C / s		
Time over melting temperature (T_L) time (t_L)	217°C 60 – 150 s		
Peak temperature (T _P)	max. 260°C (+0°C)		
Time within peak temperature – 5°C (tp)	20-40 s		
Gradient ramp down	max. 6°C/s		
Time difference from 25°C to peak temperature	max. 8 minutes		

The reflow soldering profile is based on the definition of Jedec J-STD-020D.

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